

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUICHI IKEDA	04/13/2021
SHOTA DAIKI	04/13/2021
KYOICHI FUJINAMI	04/13/2021
TERUHIKO NAWATA	04/13/2021
KATSUYA TESHIMA	04/08/2021
TETSUYA YAMADA	04/08/2021
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State/Country:	JAPAN
Postal Code:	7458648
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Street Address:	3-1-1, ASAHI, MATSUMOTO-SHI
City:	NAGANO
State/Country:	JAPAN
Postal Code:	3908621
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17312567
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	ROBERT A. GOETZ
SIGNATURE:	/Robert A. Goetz/
DATE SIGNED:	06/10/2021
Total Attachments: 2 source=TKY20023US_Assignment_uspto#page1.tif source=TKY20023US_Assignment_uspto#page2.tif	

ASSIGNMENT

WHEREAS, WE, **IKEDA, Yuichi; DAIKI, Shota; FUJINAMI, Kyoichi; NAWATA, Teruhiko; TESHIMA, Katsuya; and YAMADA, Tetsuya**, hereinafter referred to as "ASSIGNOR," have invented certain new and useful improvements as described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: **HEXAGONAL BORON NITRIDE POWDER, RESIN COMPOSITION, RESIN SHEET, AND METHOD FOR PRODUCING HEXAGONAL BORON NITRIDE POWDER**

U.S. Patent Application No. 17/312,567
International Patent Application No. PCT/JP2020/008288

Filing Date: June 10, 2021
Filing Date: February 28, 2020

WHEREAS, **TOKUYAMA CORPORATION**, a corporation of Japan having a place of business at **1-1, Mikage-cho, Shunan-shi, Yamaguchi 7458648 Japan**; and **SHINSHU UNIVERSITY**, a corporation of Japan having a place of business at **3-1-1, Asahi, Matsumoto-shi, Nagano 3908621 Japan**, hereinafter referred to as "ASSIGNEE," is desirous of acquiring the entire right, title and interest in said invention and application and in any Letters Patent which may be granted on the same; We hereby authorize our Attorney of Record to insert the Application Serial No. and Filing Date in spaces above when known;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged, ASSIGNORS have sold, assigned and transferred, and by these presents do sell, assign and transfer unto said ASSIGNEE, and ASSIGNEE's successors and assigns, all right, title and interest in and to said invention, said application for United States Letters Patent, and any Letters Patent which may hereafter be granted on the same in the United States and all countries throughout the world, including any divisions, renewals, continuations in whole or in part, substitutions, conversions, reissues, or prolongations or extensions thereof, said interest to be held and enjoyed by said ASSIGNEE as fully and exclusively as it would have been held and enjoyed by said ASSIGNORS had this assignment and transfer not been made, to the full extent and term of any Letters Patent. Authorization is given to our attorneys to insert the U.S. Patent Application No. in the space provided when known.

ASSIGNOR further agrees that ASSIGNOR will, without charge to said ASSIGNEE, but at ASSIGNEE's expense, cooperate with ASSIGNEE in the prosecution of said application and/or applications; execute, verify, acknowledge, and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof; and perform such other acts as ASSIGNEE lawfully may request, to obtain or maintain Letters Patent for said invention and improvement in any and all countries, and to vest title thereto in said ASSIGNEE, or ASSIGNEE's successors and assigns.

IN TESTIMONY WHEREOF, ASSIGNOR has hereunto signed ASSIGNOR's name to this Assignment on the date indicated below.

Ikeda Yuichi April 13, 2021
IKEDA, Yuichi Date

Daiki Shota April 13, 2021
DAIKI, Shota Date

Kyoichi Fujinami April 13, 2021
FUJINAMI, Kyoichi Date

Teruhiko Nawata April 13, 2021
NAWATA, Teruhiko Date

TESHIMA, Katsuya Date

YAMADA, Tetsuya Date

ASSIGNMENT

WHEREAS, WE, **IKEDA, Yuichi; DAIKI, Shota; FUJINAMI, Kyoichi; NAWATA, Teruhiko; TESHIMA, Katsuya; and YAMADA, Tetsuya**, hereinafter referred to as "ASSIGNOR," have invented certain new and useful improvements as described and set forth in the below-identified application for United States Letters Patent:

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NOW THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged, ASSIGNORS have sold, assigned and transferred, and by these presents do sell, assign and transfer unto said ASSIGNEE, and ASSIGNEE's successors and assigns, all right, title and interest in and to said invention, said application for United States Letters Patent, and any Letters Patent which may hereafter be granted on the same in the United States and all countries throughout the world, including any divisions, renewals, continuations in whole or in part, substitutions, conversions, reissues, or prolongations or extensions thereof, said interest to be held and enjoyed by said ASSIGNEE as fully and exclusively as it would have been held and enjoyed by said ASSIGNORS had this assignment and transfer not been made, to the full extent and term of any Letters Patent. Authorization is given to our attorneys to insert the U.S. Patent Application No. in the space provided when known.

ASSIGNOR further agrees that ASSIGNOR will, without charge to said ASSIGNEE, but at ASSIGNEE's expense, cooperate with ASSIGNEE in the prosecution of said application and/or applications; execute, verify, acknowledge, and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof; and perform such other acts as ASSIGNEE lawfully may request, to obtain or maintain Letters Patent for said invention and improvement in any and all countries, and to vest title thereto in said ASSIGNEE, or ASSIGNEE's successors and assigns.

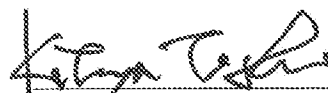
IN TESTIMONY WHEREOF, ASSIGNOR has hereunto signed ASSIGNOR's name to this Assignment on the date indicated below.

IKEDA, Yuichi Date

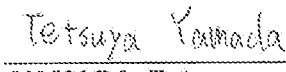
DAIKI, Shota Date

FUJINAMI, Kyoichi Date

NAWATA, Teruhiko Date



TESHIMA, Katsuya Date



YAMADA, Tetsuya Date